

IMPROVED VIA ADHESION IN MULTILAYER
MEMS STRUCTURE
Inventor: Rabah Mezenner
Attorney Docket: TI-33824
(032350.B550)

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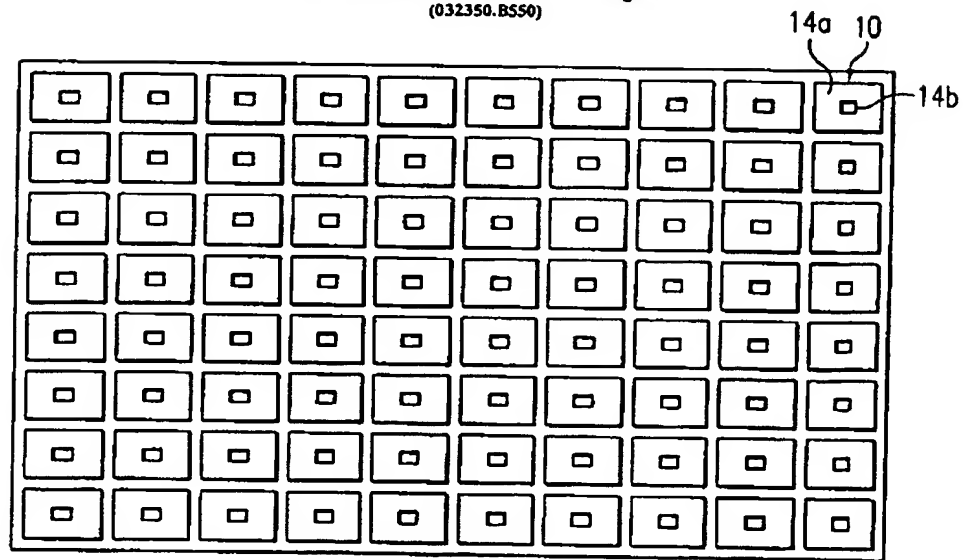


FIG. 11

110

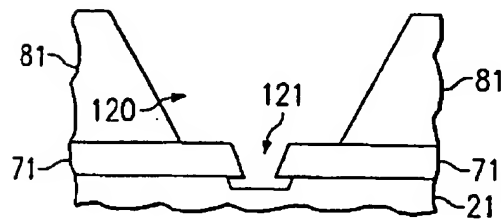


FIG. 12

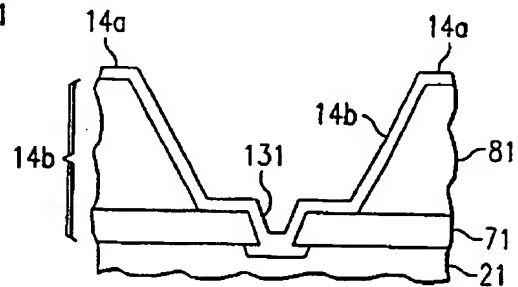


FIG. 13

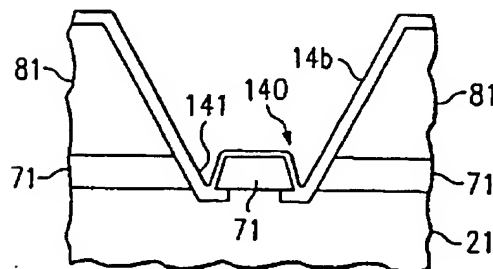


FIG. 14